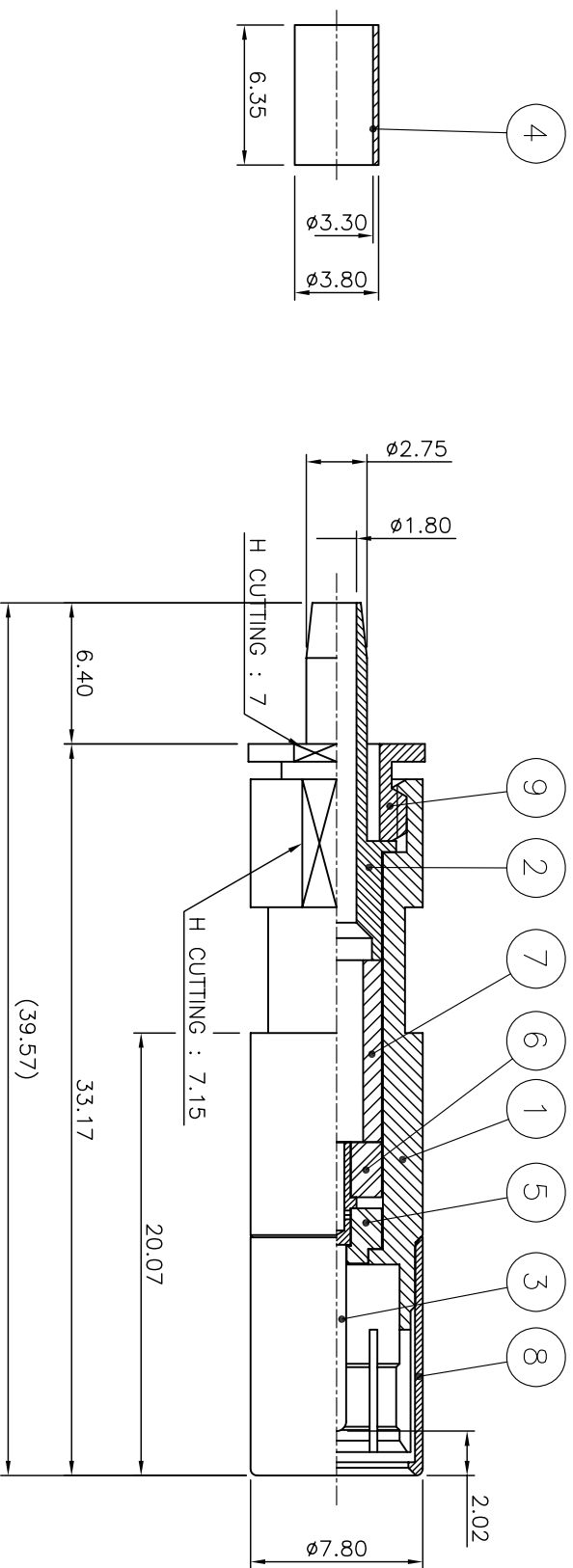


REVISION			
REV	DESCRIPTION	DRAWN	APPR
1/R	초도작성	E.H.KIM	I.C.KIM
			DATE
			2012.10.24



9	BACK NUT	1	MBsBD	Gold Plate	DBN00183-5/1
8	CAP	1	MBsBD	Gold Plate	DCU02197-5/1
7	INSERT	1	MBsBD	Gold Plate	DIS00188-5/1
6	INSULATOR	1	TEFLON		DIN02089-N/1
5	INSULATOR	1	TEFLON		DIN02088-N/1
4	FERRULE	1	MBsBD	Gold Plate	DFE00169-5/1
3	CONTACT	1	MBsBD	Gold Plate	DCT02687-5/1
2	BODY	1	MBsBD	Gold Plate	DBD03180-5/1
1	BODY	1	MBsBD	Gold Plate	DBD03179-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

DATE 2012. 10. 24

APPROVED BY I. C. KIM

CHECKED BY

DRAWN BY E. H. KIM

SCALE 3/1 UNIT mm

FINISH -

KU COMTECH
RF & MICROWAVE TECHNOLOGY
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Fax : 82-32-347-8017

TITLE 기타 CABLE PS Crimp 접점조립체

DWG NO. CN02879-7/1

REVISION 1 SHEET 1 of 1